This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. **(Previously Presented)** An electroplating solution for copper comprising $CuSO_4 \cdot 5H_2O$, H_2SO_4, HCl, polyethylene glycol with a molecular weight greater than 200, hydroxyl amine sulfate, and hydroxyl amine chloride.

2. **(Currently Amended)** ~~A~~ An electroplating solution according to claim 1 further comprising Cl^- ions in a range of 50 – 150 ppm and wherein the hydroxyl amine sulfate is in a range of 0.01 – 5 g/l.

3. **(Currently Amended)** ~~A~~ An electroplating solution according to claim 1 further comprising Cl^- ions derived at least from the HCl in a range of 55 – 125 ppm.

4. **(Previously Presented)** An electroplating solution according to claim 1, further comprising an additive.

5. **(Currently Amended)** A solution according to claim 4, wherein the additive is thiourea, molasses, glucose, tribenzylamine, benzotriazole, or naphthalene sulfonic acid~~, or $(NH_2OH)_2 \cdot H_2SO_4$~~.

6. (Currently Amended) An electroplating solution ~~made by~~ comprising adding together:

$CuSO_4 \cdot 5H_2O$;

H_2SO_4;

HCl~~, and~~;

optionally an additive; and

polyethylene glycol with a molecular weight greater than 200, and either hydroxyl amine sulfate or hydroxyl amine chloride.

7. (Currently Amended) An electroplating solution comprising:

$CuSO_4 \cdot 5H_2O$;

H_2SO_4;

Cl^- ions~~, and~~;

polyethylene glycol with a molecular weight greater than 200; and

hydroxyl amine sulfate or hydroxyl amine chloride.

8. (Currently Amended) An electroplating solution according to claim 7, wherein the concentration of ~~$CuSO_4 \cdot 5H_20$~~ $CuSO_4 \cdot 5H_2O$ is 60 – 150 g/l, H_2SO_4 is 80 – 150 g/l, Cl^- ions are 50 – 150 ppm, and polyethylene glycol is less than 100 ppm~~, and optionally an additive~~.

9. (Canceled)